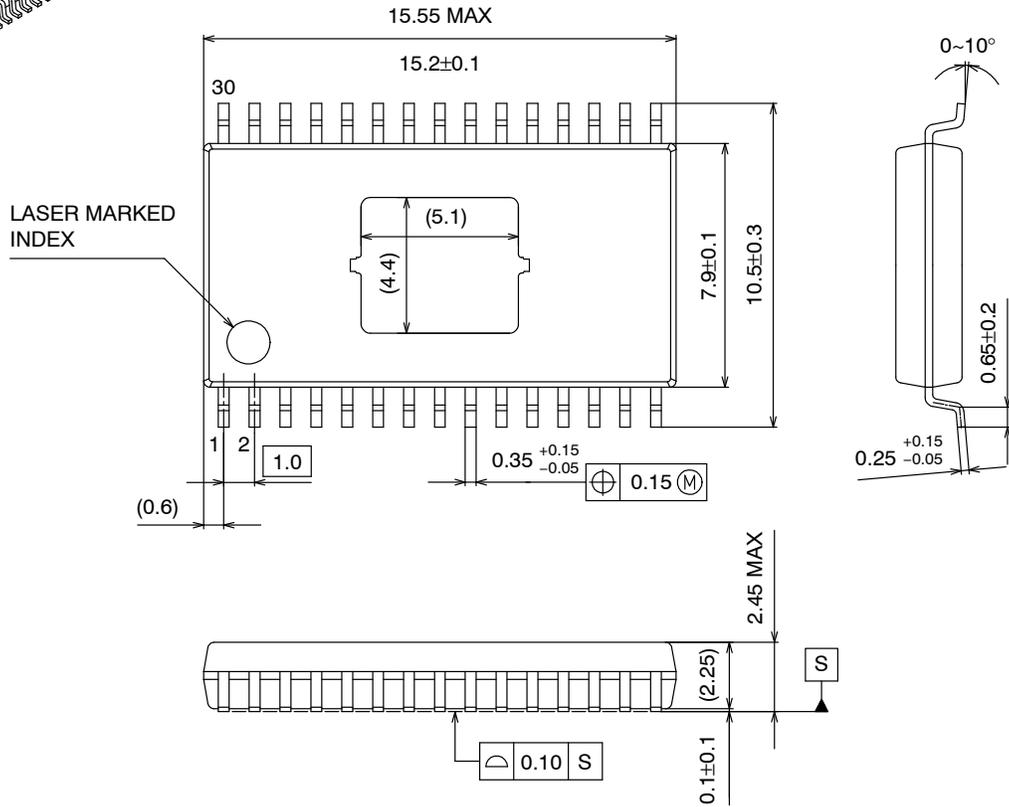
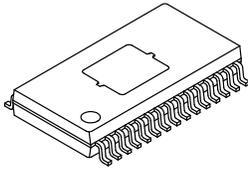


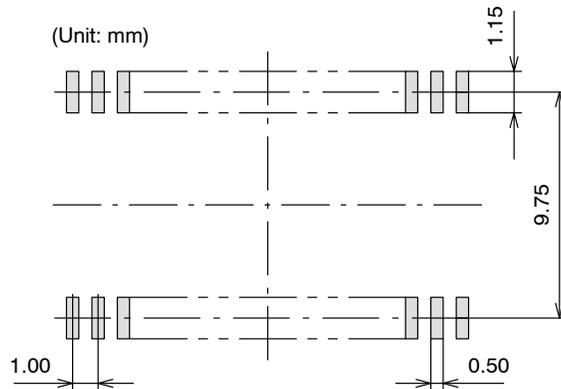
**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

**SOIC30 W / MFP30KR (375 mil)**  
**CASE 751CH**  
**ISSUE A**

DATE 08 NOV 2013



**SOLDERING FOOTPRINT\***



NOTE: The measurements are not to guarantee but for reference only.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

|                         |                                     |  |
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| <b>DESCRIPTION:</b>     | <b>SOIC30 W / MFP30KR (375 MIL)</b> | <b>PAGE 1 OF 2</b>   |

